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U.S. PATENT AND TRADEMARK OFFICE

U.S. PTO  
09/16/98  
09/23/98

Case Docket No. 981187

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

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PATENTS ONLY

To the Assistant Commissioner for Patents.  
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

**Hideki MIZUHARA, Hiroyuki WATANABE and Naoteru MATSUBARA**

Additional name(s) of conveying party(ies) attached? NO

2. Name and address of receiving party(ies):

Name: **SANYO ELECTRIC CO., LTD.**

Street Address:

5-5, Keihanhondori 2-chome, Moriguchi-shi,  
Osaka, Japan

Additional name(s) & address(es) attached? NO

3. Nature of conveyance: **Assignment**

Execution Date: **September 17, 1998**

4. Title: **SEMICONDUCTOR DEVICE INCLUDING INSULATION FILM AND  
FABRICATION METHOD THEREOF**

5. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: September 17, 1998

A. Patent Application No.(s)      B. Patent No.(s)

Additional numbers attached? NO

1/30/1998 DNE:HI 00000001 09110044  
10.00 0P

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,  
McLeland & Naughton  
Suite 1000  
1725 K Street, N.W.  
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

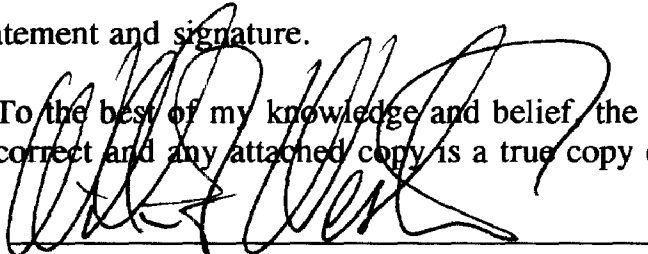
8. Total fee (37 CFR 3.41). . . . . \$ **40.00**

XX Check enclosed

9. Deposit Account No.: 01-2340

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



William F. Westerman  
Reg. No.: 29,988

Date September 25, 1998

Total number of pages including cover sheet: 4

WFW/yap

**ASSIGNMENT**

Serial No. \_\_\_\_\_

Filed \_\_\_\_\_

WHEREAS, Hideki MIZUHARA, Hiroyuki WATANABE and  
Naoteru MATSUBARA

**Insert Name(s)  
of Inventor(s)**

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements

**Insert Title  
of Invention**

in Semiconductor Device Including Insulation Film and  
Fabrication Method Thereof

**Insert Date  
of Signing of  
Application**

for which an application for Letters Patent of the United States of America has been executed by the  
undersigned on September 17, 1998 ; and

WHEREAS, Sanyo Electric Co., Ltd.

**Insert Name  
of Assignee**

**Insert Address  
of Assignee**

of 5-5, Keihanhondori 2-chome, Moriguchi-shi, Osaka, Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories, dependencies and possessions and the entire right, title and interest and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention of the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) the request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Armstrong, Westerman, Hattori, McLeland & Naughton the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

Date September 17, 1998, Name of Inventor Hideki Mizuhara  
(signature) Hideki MIZUHARA

Date September 17, 1998, Name of Inventor Hiroyuki Watanabe  
(signature) Hiroyuki WATANABE

Date September 17, 1998, Name of Inventor Naoteru Matsubara  
(signature) Naoteru MATSUBARA

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)

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(signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)